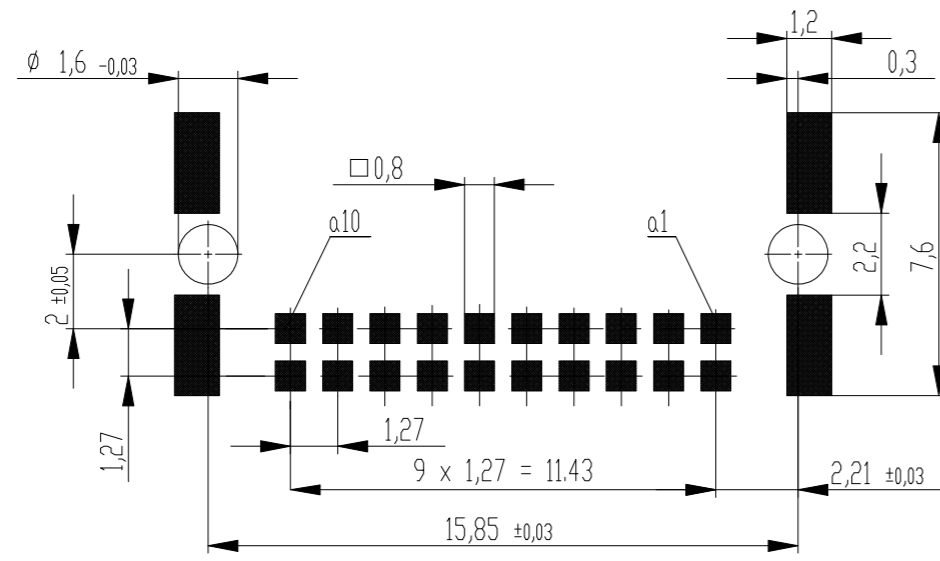
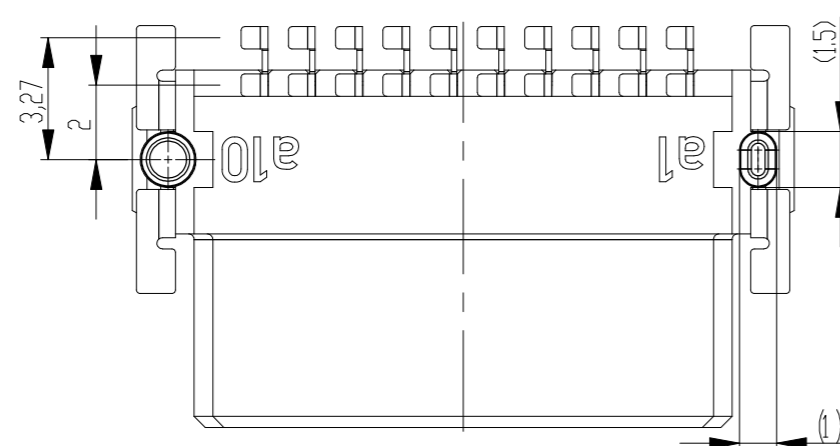
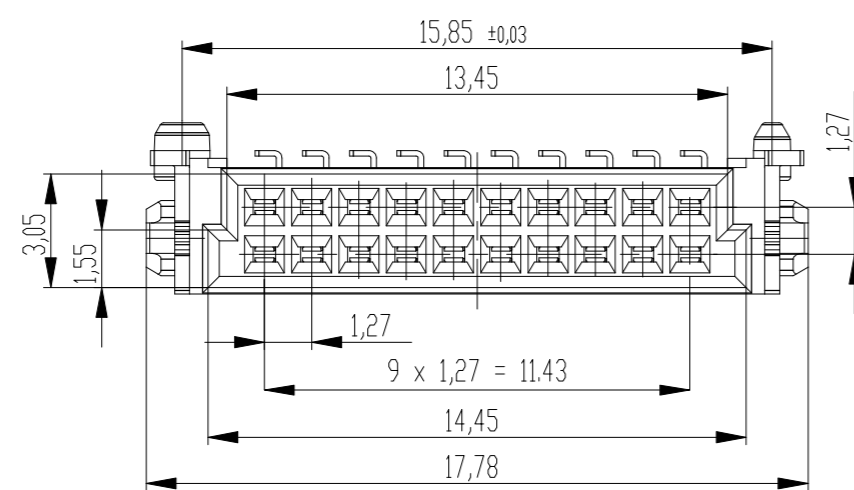
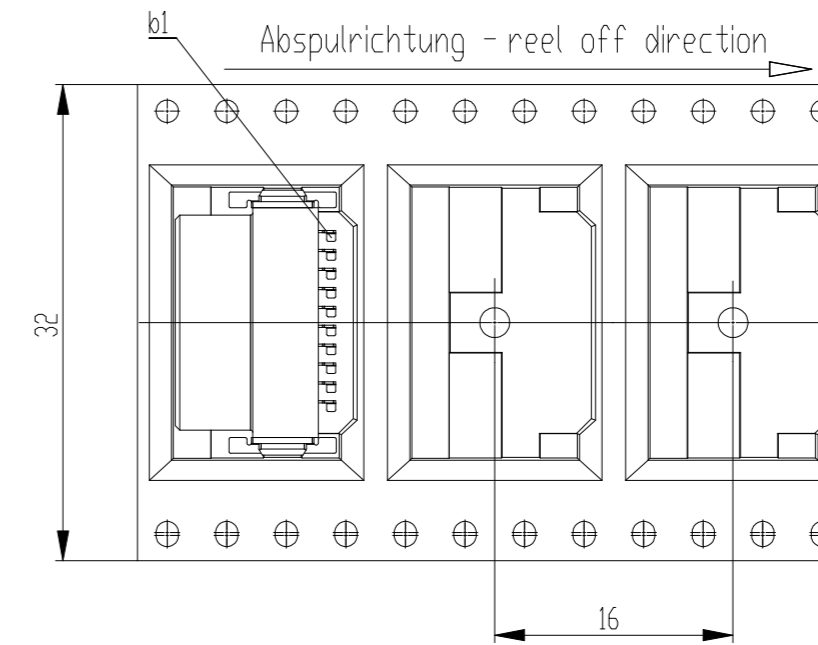
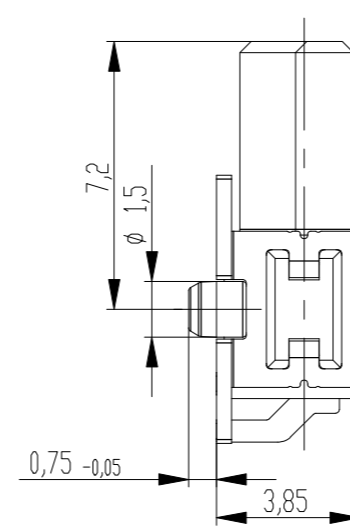
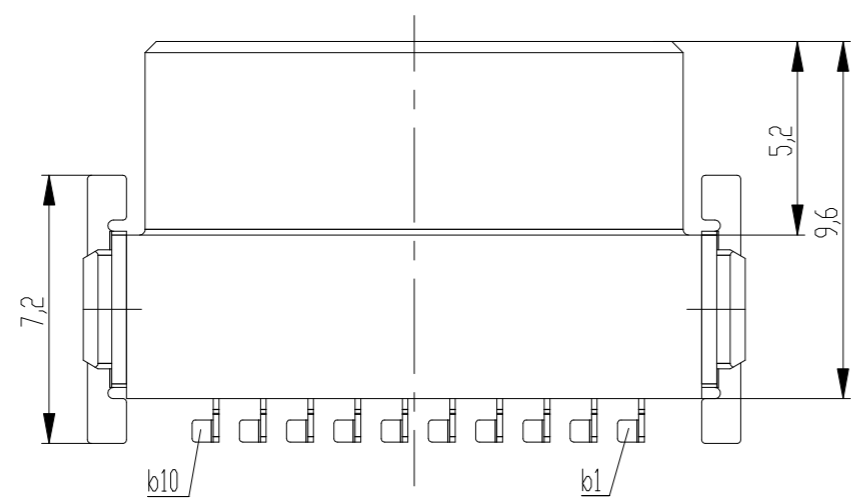
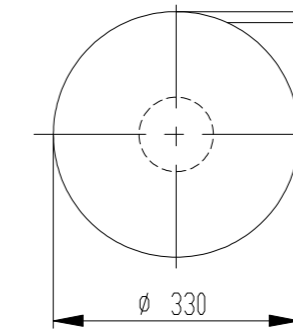


Leiterplatten-Layout Vorschlag für SMT  
PCB-Layout Proposal for SMT



Verpackt im Gurt in Anlehnung an DIN IEC 60286-3  
tape on reel packaging according to DIN IEC 60286-3  
Verpackungseinheit: 560 Stück  
packaging unit: 560 pcs



Anforderungsstufe 1  
performance level 1

Kontaktbereich vergoldet  
mating area gold plating

Anschlussbereich verzinkt 4-6 µm  
terminal area 4-6 µm tin plating

Koplanarität der Anschlüsse ≤ 0,1 mm  
coplanarity area of termination ≤ 0,1 mm

BA7-03 - Standard Bauhöhe  
type7-03 - standard assembly height

Übersichts- und Einzelansichten dieser Zeichnung sind als öffentliche Dokumente zu betrachten. Die Weitergabe dieser Zeichnung ist ohne schriftliche Genehmigung der STE-Connectivity GmbH untersagt. In case of any deviation the English version shall prevail.

Dimension no.	Tolerances Dim. for Information ISO 8015		Scale 5:1 Material
Customer drawing: THIS DRAWING IS A CONTROLLED DOCUMENT.	Subject to modification without prior notice. Drawing will not be updated.		ERNI-Federl. SMC-Q 20-SMD-BA7-03 Female SMC-Q 20-SMD-type7-03
c Index	07.02.2020 Date		©= 354079-E 1 A2
Class			SMCQ